Qualification Results Summary of the Wafer Level Capping of the ADXL103, ADXL203, ADXL204, ADXL212 and the ADXL213

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| --- | --- | --- | --- |
| QUALIFICATION RESULTS | | | |
| Test | Conditions | Sample Size | Results |
| Early Life Failure Rate (ELFR) | Mil-Std-883 Method 1015 | **2000** | **Pass** |
| Group D Sub-Group 4 | Mil-Std-883 Method 5005 | **3x17** | **Pass** |
| Group D Sub-Group 6 | Mil-Std-883 Method 5005 | **3X5** | **Pass** |
| Highly Accelerated Stress Test (HAST)\* | JEDEC*JESD22-A110* | **3x77** | **Pass** |
| Temperature Cycle (TC)\* | JEDEC*JESD22-A104* | **12x77** | **Pass** |
| Autoclave (AC)\* | JEDEC *JESD22-A102* | **4x77** | **Pass** |
| High Temperature Storage Life (HTSL) | JEDEC *JESD22-A103* | **1x200**  **9x77** | **Pass** |
| Low Temperature Storage Life (LTS) | JEDEC JESD22-A119 | **6x77** | **Pass** |
| Random Drop | AEC-Q100 Test G5 | **3X45** | **Pass** |
| Solder Heat Resistance  (SHR)\* | *JEDEC/IPC J-STD-020* | **3x30** | **Pass** |

\*Preconditioned to JEDEC Std-20 MSL 3